Abstract

Method for polishing a semiconductor wafer

The invention relates to a method for polishing a semiconductor wafer having a front side and a rear side. The method comprises polishing the rear side of the semiconductor wafer by means of CMP, which involves producing a material removal with a profile along the diameter of the semiconductor wafer according to which the material removal is higher in a center region of the rear side than in an edge region of the rear side; and polishing the front side of the semiconductor wafer by means of CMP, which involves producing a material removal with a profile along the diameter of the semiconductor wafer according to which the material removal is lower in a center region of the front side than in an edge region of the front side.

Fig. 5